

KL 5300 series – run sheet

KemLab Inc.

nanyte.com/photoresists/kl-5300 · last updated 2026-07-26

Thickness: 0.1–2.5 μm

Softbake: 105 °C · 60 s · hotplate

Post-exposure bake: 115 °C · 60 s

Develop: Developer 0.26N TMAH